

43rd IEEE VLSI Test Symposium 2025



RELIABILITY AND SECURITY CHALLENGES IN VLSI SYST

CALL FOR PAPERS

The IEEE VLSI Test Symposium (VTS) explores emerging trends and novel concepts in test, reliability, calibration, validation, yield, and security of microelectronic circuits and systems. The VTS Program Committee invites original - unpublished paper submissions for VTS 2025 Proposals for the innovative practices and special session tracks are also invited. For more information, visit the website: https://tttc-vts.org/public_html/new/2025/

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Major topics include but are not limited to:

- Generative AI Applications in Test & Security Defect & Fault Tolerance
- Silicon Lifecycle Management
- · Silent Data Corruption
- · Test-Enabled Digital Twin
- Analog Mixed-Signal RF Test
- ATPG & Compression
- Automotive Test & Safety
- Built-In Self-Test (BIST)
- Functional safety
- Digital Twin Enabled Test & Security
- · Testing for Extreme Environments
- Test for Non-Si & Compound Circuits
- On-Line Test & Error Correction
- Power & Thermal Issues in Test
- System-on-Chip (SOC) Test
- · Test & Reliability of Biomedical Devices
- Test & Reliability of High-Speed I/O
- Test Standards
- FPGA Test
- Defect-Based Test

- - Delay & Performance Test
- · Design for Testability
- · Post-silicon Validation & Debug
- Hardware Security
- Embedded System & Board Test
- Test & Security of Quantum Circuits
- Test & Security of Photonic Circuits
- **Test & Security of Emerging Memory** Technologies
- High BW Test through High-Speed Interfaces
 Test & Security of Machine Learning Hardware
 - Machine Learning for Test & Security
 - · Functional Debug through Scan
 - · Fault Modeling and Simulation
 - Low-Power IC Test
 - Microsystems/MEMS/Sensors Test
 - Memory Test and Repair
 - Test for 3D & Heterogeneous Integration
 - Yield Optimization

Scientific Papers: complete manuscripts - up to 6 pages in

standard IEEE two-column format (references do not count

Submissions: **Key Dates:**

Paper registration:

Nov. 18, 2024

Paper PDF upload:

Nov. 25, 2024

Notification:

Jan. 31, 2025

Feb. 21, 2025

Camera-ready upload:

The VTS review process is DOUBLE BLIND

Special Session and Innovative Practices Proposals:

Proposals may include presentations on hot topics, panels, and embedded tutorials. Every proposal must include a 150-to-200 word abstract - the name of the organizers and a list of at least

three speakers with tentative presentation titles.

Submit your papers at:

towards the page limit).

https://welcome.molesystems.com/tttc/VTS/2025

General Chairs

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